

# 623-0286-H11 General Specifications

## ■ Mechanical

- Typical Application: BGA
- Minimum Device Pitch: 0.40 mm
- Force: 19.2 gf @ 0.50 mm Recommended Travel
- Operating Temperature Range: -55°C to 120°C
- Device Side Contact: 4-point Crown Tip
- PCB Side Contact : Conical Radius Tip

## ■ Electrical

- Bandwidth @ -1 dB: up to 17.5 GHz
  - Based on G-S-G Pattern
- Contact Resistance: < 60 mΩ average
- Current Carrying Capability: 2.5 A
  - Measured in free air

## ■ Plating

- Device Side Plunger: Homogenous alloy
- PCB Side Plunger : Gold plated
- Barrel: Gold plated
- Spring: Gold plated

